IN THE SPECIFICATION:

Page 1, line 2: ~~SUBSTRATE FOR LIGHT EMITTING DIODE~~ METHOD FOR MANUFACTURING SUBSTRATES FOR LIGHT EMITTING DIODES.

lines 5-7:

The present invention relates to a ~~substrate~~ method for manufacturing a plurality of substrates for a light emitting diode (LED) used in an electronic instrument such as a portable telephone.

lines 13-19:

Fig. 15 is a perspective view showing a conventional substrate for an LED. The substrate comprises a metal base 51 made of copper or aluminum, an insulation layer 52 of prepreg adhered on the metal base 51, circuit patterns 53 and 54 made of copper foil on which gold is plated. An LED 70 is mounted on the circuit pattern 53 and connected to the circuit pattern 54 by a wire 71.

Page 2, lines 8-9:

An object of the present invention is to provide a ~~substrate having a high heat radiation property~~ method for manufacturing a plurality of substrates having excellent heat insulation performance.

Page 3, lines 5-21:

Fig. 1 is a perspective view of a substrate according to a first ~~embodiment~~ example of a substrate manufactured by the method of the present invention;

Figs. 2 and 3 are perspective views showing a preparation of metal bases;

Figs. 4 through 9 are perspective views showing a method ~~for manufacturing the substrate~~ according to a first embodiment of the invention;

Fig. 10 is a perspective view showing a substrate ~~according to a second embodiment~~ of a second example;

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Figs. 11 through 13 are perspective views showing a manufacturing method of ~~the substrate of the~~ a second embodiment;

Fig. 14 is a perspective view showing a substrate according to a third ~~embodiment~~ example;

Fig. 15 is a perspective view showing a conventional substrate for an LED; and

Fig. 16 is a perspective view showing another substrate.

lines 24-25:

Fig. 1 is a perspective view of a substrate ~~according to~~ made by a first ~~embodiment~~ example of the present invention.

Page 4, lines 8-10:

The LED 40 on the circuit patterns 4a and 4b is connected to the terminal electrodes ~~6a and~~ 6b by through holes 5 passing through the metal bases 1a and 1b.

Page 5, lines 20-21:

Fig. 10 is a perspective view showing a substrate according to a second ~~embodiment~~ example.

Page 6, lines 15-16:

Fig. 14 is a perspective view showing a substrate according to a third ~~embodiment~~ example of the present invention.

Page 6, line 27-page 7, line 2:

In the substrate of the third ~~embodiment~~ example, the sizes of the metal bases 30a and 30b are different in sectional shape, thereby deflecting the position of the first heat insulation layer from the center line.

Page 7, lines 14-17:

In accordance with the present invention, a substrate is excellent in heat radiation performance, heat insulation performance and ~~rely~~ reliability can by obtained.

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